

Property	Typical Value [1] RO4725JXR	Typical Value [1] RO4730JXR	Typical Value [1] RO4730G3	Direction	Units	Condition	Test Method	
<b>Dielectric Constant, <math>\epsilon_r</math> Process</b>	2.55 ± 0.05	3.00 ± 0.05	3.00 ± 0.05	Z		10 GHz/23°C	IPC-TM-650, 2.5.5.5	
<b>Dielectric Constant, <math>\epsilon_r</math> Design [3]</b>	2.64	2.98	2.98	Z		1.7 GHz - 5 GHz	Differential Phase Length Method	
<b>Dissipation Factor [4]</b>	0.0026	0.0027	0.0029	Z		10 GHz/23°C	IPC-TM-650, 2.5.5.5	
	0.0022	0.0023	0.0023			2.5GHz		
<b>Thermal Coefficient of <math>\epsilon_r</math></b>	+34	+32	+26	Z	ppm/°C	-50°C to 150°C	IPC-TM-650, 2.5.5.5	
<b>Volume Resistivity (0.030")</b>	2.16 X 10 <sup>8</sup>	5.96 X 10 <sup>8</sup>	4.78 x 10 <sup>8</sup>		MΩ·cm	COND A	IPC-TM-650, 2.5.17.1	
<b>Surface Resistivity (0.030")</b>	4.8 X 10 <sup>7</sup>	1.68 X 10 <sup>8</sup>	2.78 x 10 <sup>8</sup>		MΩ	COND A	IPC-TM-650, 2.5.17.1	
<b>PIM [2]</b>	-166	-164	-165		dBc	50 ohm 0.060"	43dBm 1900MHz	
<b>Electrical Strength (0.030")</b>	630	721	762	Z	V/mil		IPC-TM-650, 2.5.6.2	
<b>Flexural Strength</b>	<b>MD</b>	121 (17.5)	167 (24.2)	209 (30.3)	MPa (kpsi)	RT	ASTM D790	
	<b>CMD</b>	92 (13.3)	135 (19.6)	152 (22.1)				
<b>Dimensional Stability</b>	<0.4	<0.4	<0.4	X,Y	mm/m	after etch +E2/150°C	IPC-TM-650, 2.4.39A	
<b>Coefficient of Thermal Expansion</b>		13.9	11.3	13.7	ppm/°C	-55 TO 288°C	IPC-TM-650, 2.1.24	
		19.0	13.5	14.7				Y
		25.6	21.1	30.3				Z
<b>Thermal Conductivity</b>	0.38	0.49	0.42	Z	W/mK°	50°C	ASTM D5470	
<b>Moisture Absorption</b>	0.24%	0.14%	0.15%		%	48/50	IPC-TM-650 2.6.2.1 ASTM D570	
<b>Tg</b>	>280	>280	>280		°C		IPC-TM-650 2.4.24	
<b>Td</b>	439	443	417		°C		ASTM D3850	
<b>Density</b>	1.27	1.53	1.58		gm/cm <sup>3</sup>		ASTM D792	
<b>Copper Peel Strength</b>	8.5	8.4	5.0		pli	1 oz LoPro EDC	IPC-TM-650 2.4.8	
<b>Flammability</b>	N/A	N/A	Yes				UL94	
<b>Lead-Free Process Compatible</b>	YES	Yes	Yes					

NOTES: [1] Typical values are a representation of an average value for the population of the property. For specification values contact Rogers Corporation.  
 [2] Using Rogers' internal test method on a 0.0607" laminate.  
 [3] The design Dk is an average number from several different tested lots of material and on the most common thickness/s. If more detailed information is required please contact Rogers Corporation.  
 [4] Using LoPro Reverse Treated EDC Foil

Standard Thicknesses			Standard Panel Sizes:		Standard Copper Cladding
RO4725JXR	RO4730JXR	RO4730G3			
LoPro Copper 0.0307" (0.780mm) 0.0607" (1.542mm)	LoPro Copper 0.0207" (0.526mm) 0.0307" (0.780mm) 0.0407" (1.034mm) 0.0607" (1.542mm)	LoPro Copper 0.0057" (0.145mm) 0.0107" (0.272mm) 0.0207" (0.526mm) 0.0307" (0.780mm) 0.0407" (1.034mm) 0.0607" (1.542mm)	ED Copper 0.0200" (0.508mm) 0.0300" (0.762mm) 0.0400" (1.016mm) 0.0500" (1.270mm) 0.0600" (1.524mm)	12" X 18" (305 X 457 mm) 24" X 18" (610 X 457 mm) 24" X 36" (610 X 915 mm) 48" X 36" (1.224m X 915mm) Larger sizes may be available	LoPro Reverse Treated EDC Foil ½ oz (18µm), 1 oz (35µm)  Standard EDC (RO4730G3 only) ½ oz (18µm), 1 oz (35µm)

For pcb technical problems, ipcb knowledgeable support team is here to help you with every step.

You can also request pcb quotation here.

\*Visit the ipcb website: [www.ipcb.com](http://www.ipcb.com)

\*Contact ipcb by E-mail: [sales@ipcb.com](mailto:sales@ipcb.com)